

FEATURES :

- LOW INTERMODULATION DISTORTION
IM₃ = -45 dBc at P_o = 31.5 dBm,
Single Carrier Level
- HIGH POWER
P_{1dB} = 42.5 dBm at 7.7 GHz to 8.5 GHz
- HIGH EFFICIENCY
η_{add} = 29 % at 7.7 GHz to 8.5 GHz
- HIGH GAIN
G_{1dB} = 5.5 dB at 7.7 GHz to 8.5 GHz
- BROAD BAND INTERNALLY MATCHED
- HERMETICALLY SEALED PACKAGE

RF PERFORMANCE SPECIFICATIONS (Ta = 25°C)

CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Output Power at 1 dB Compression Point	P _{1dB}	V _{DS} = 10 V f = 7.7~8.5 GHz	dBm	41.5	42.5	—
Power Gain at 1 dB Compression Point	G _{1dB}		dB	4.5	5.5	—
Drain Current	I _{DS}		A	—	4.4	5.0
Gain Flatness	ΔG		dB	—	—	±0.8
Power Added Efficiency	η _{add}		%	—	29	—
3rd Order Intermodulation Distortion	IM ₃	Note 1	dBc	-42	-45	—
Channel-Temperature Rise	ΔT _{ch}	V _{DS} × I _{DS} × R _{th} (c-c)	°C	—	—	80

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	V _{DS} = 3 V I _{DS} = 6.0 A	mS	—	3600	—
Pinch-off Voltage	V _{GSoff}	V _{DS} = 3 V I _{DS} = 60 mA	V	-1	-2.5	-4.0
Saturated Drain Current	I _{DSS}	V _{DS} = 3 V V _{GS} = 0 V	A	—	10.5	14.0
Gate-Source Breakdown Voltage	V _{GS0}	I _{GS} = -200 μA	V	-5	—	—
Thermal Resistance	R _{th} (c-c)	Channel to Case	°C/W	—	1.5	2.0

Note 1 : 2 tone Test Pout = 31.5 dBm Single Carrier Level.

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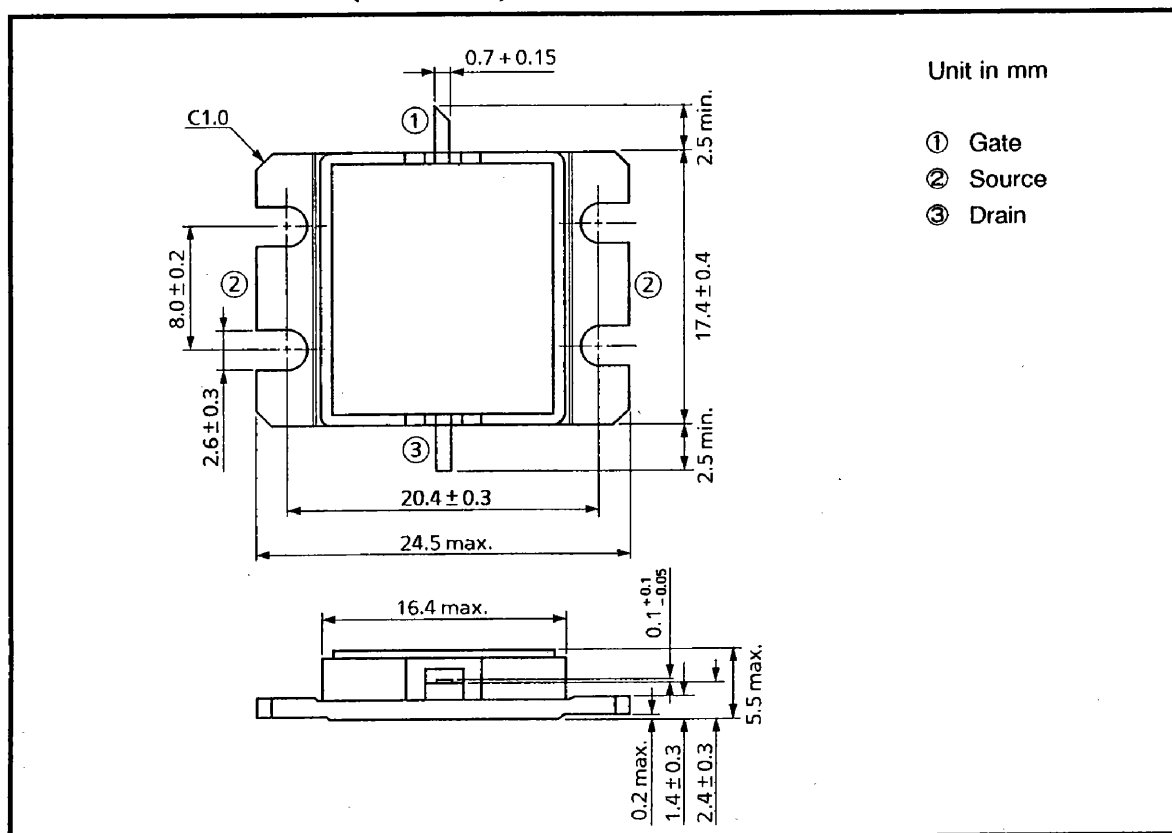


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ABSOLUTE MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	V_{DS}	V	15
Gate-Source Voltage	V_{GS}	V	-5
Drain Current	I_{DS}	A	14
Total Power Dissipation ($T_C = 25^\circ\text{C}$)	P_T	W	75
Channel Temperature	T_{ch}	$^\circ\text{C}$	175
Storage Temperature	T_{stg}	$^\circ\text{C}$	-65~175

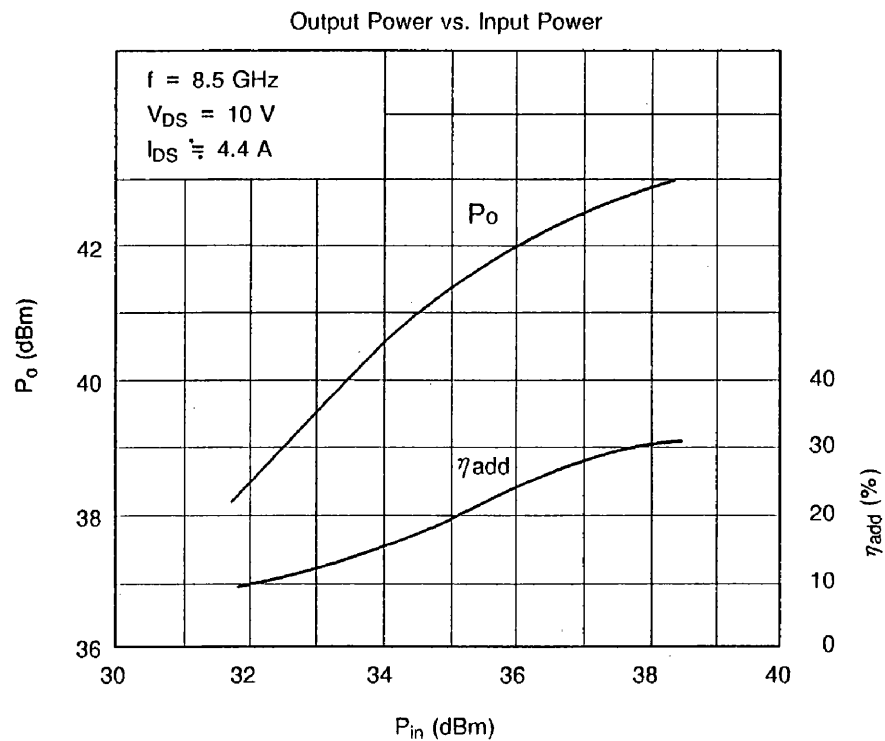
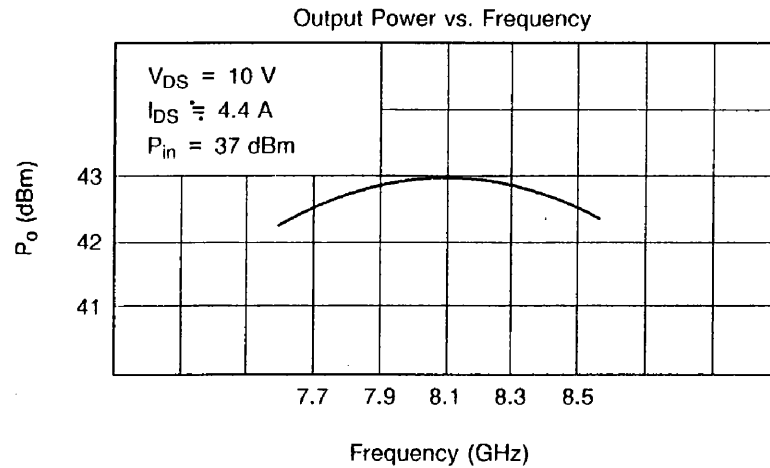
PACKAGE OUTLINE (2-16G1B)



HANDLING PRECAUTIONS FOR PACKAGED TYPE

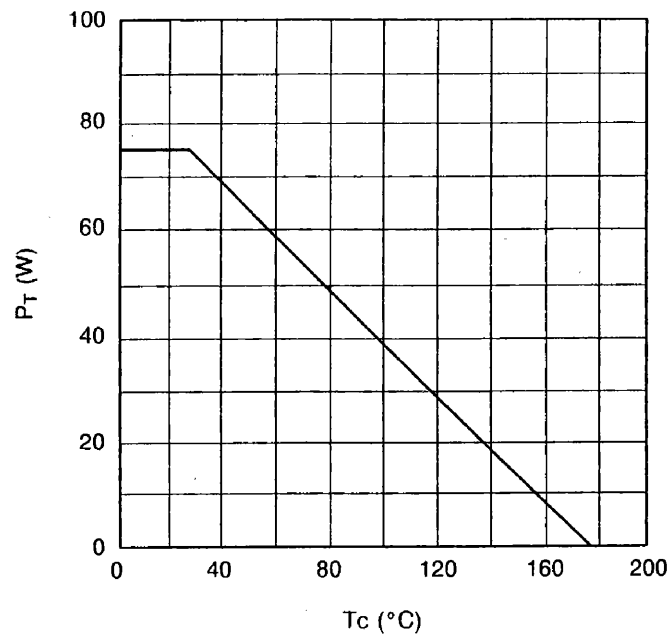
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C .

RF PERFORMANCES

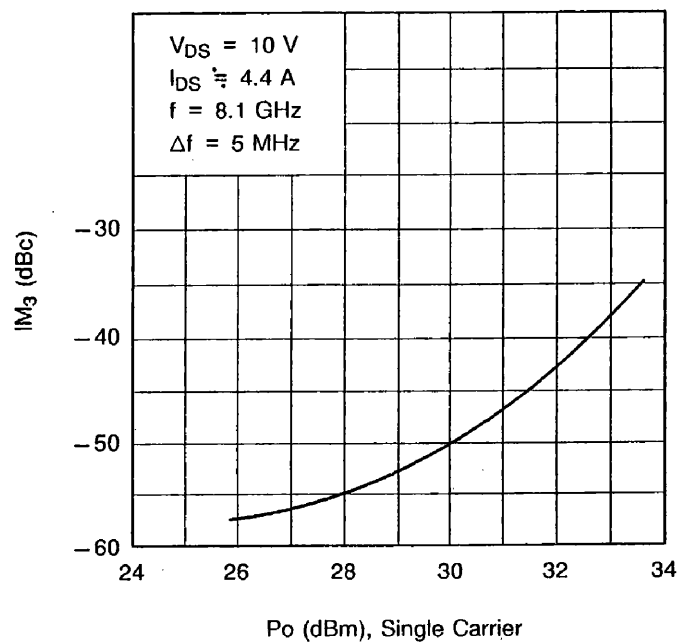


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POWER DISSIPATION VS. CASE TEMPERATURE



IM₃ VS. OUTPUT POWER CHARACTERISTICS

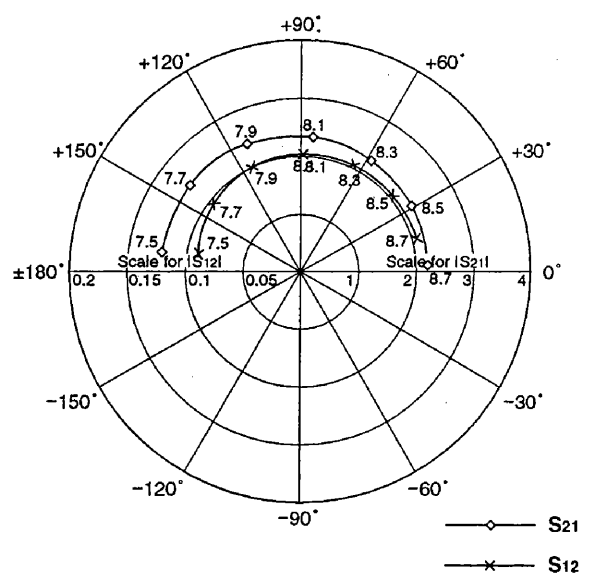
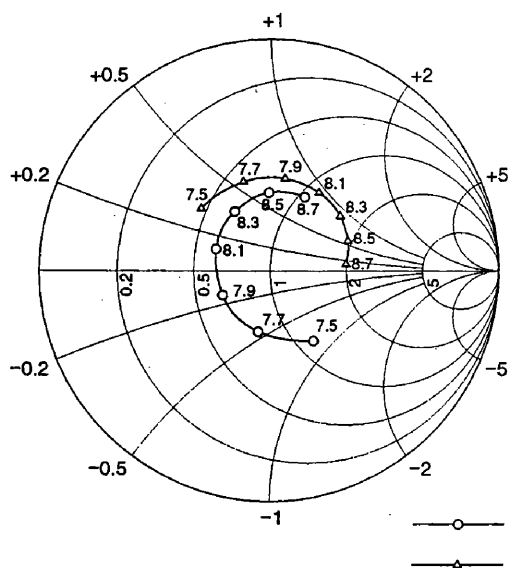


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TIM7785-16SL S-PARAMETERS (MAGN. and ANGLES)

$V_{DS} = 10V$, $I_{DS} = 4.0A$

$f = 7.5 \sim 8.7GHz$



FREQUENCY (GHz)	S ₁₁		S ₁₂		S ₂₁		S ₂₂	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
7.50	0.358	-58	0.090	170	2.427	172	0.405	138
7.70	0.269	-101	0.096	142	2.440	142	0.405	107
7.90	0.232	-153	0.100	115	2.406	113	0.406	81
8.10	0.255	158	0.102	89	2.340	85	0.401	58
8.30	0.302	121	0.103	64	2.270	58	0.388	38
8.50	0.341	91	0.103	40	2.227	31	0.364	21
8.70	0.354	65	0.104	16	2.197	3	0.333	5